



# SOT684-20

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 mm x 8 mm x 0.85 mm

24 April 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN56
<b>Package type industry code</b>	HVQFN56
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	24-4-2017
<b>Manufacturer package code</b>	98ASA00994D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	8	-	mm
E	package width	-	-	8	-	mm
A	seated height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	





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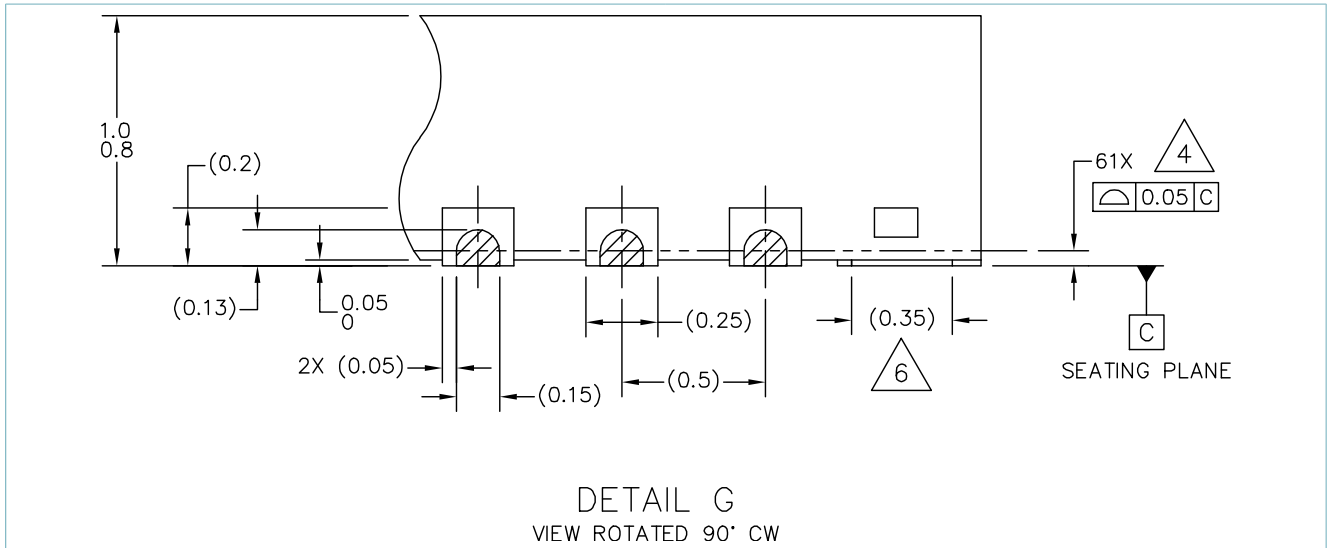


Fig. 2. Package outline dt1 HVQFN56 (SOT684-20)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN ONE CONFIGURATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH PAD AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.25 MM.
6. NON-FUNCTIONAL PADS.

Fig. 3. Package outline note HVQFN56 (SOT684-20)

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### 3. Legal information

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## 4. Contents

---

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	4

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